

⊕ 0.10 M C A B

0.10 M C A B С $0.05\,$ M

NOTE 3

E2

e > <

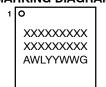
BOTTOM VIEW

DATE 12 NOV 2013

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLEHANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSIONS: MILLIMETERS. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25mm FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1	0.00	0.05	
А3	0.20 REF		
b	0.18	0.30	
D	10.00 BSC		
D2	5.85	6.15	
E	10.00 BSC		
E2	5.85	6.15	
е	0.50 BSC		
L	0.30	0.50	
L1	0.00	0.15	

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

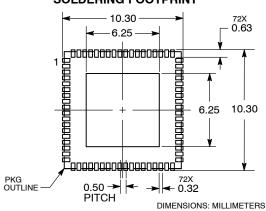
= Assembly Location

= Wafer Lot WL YY = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT



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DESCRIPTION:	QFN72 10x10, 0.5P		PAGE 1 OF 1

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